

THS4531ARUN Extended Range Revised: Thursday, February 27, 2014

CIRCUIT TYPE		Revision: A					
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Item #	Quantity	Value	Designator	Description	Manufacturer	Part Number	Digi-Key P/N
1	2	DNP	C1,C2	CAP CER 1000PF 16V 5% NPO 0402	MURATA	CL05C102JO5NNNC	1276-1636-1-ND
2	2	220pF	C3,C4	CAP CER 220PF 50V 5% NPO 0402	MURATA	C1005C0G1H221F050BA	445-7015-1-ND
3	1	2.2nF	C5	CAP CER 2200PF 50V 10% X7R 0402	MURATA	GRM155R71H222KA01D	490-1305-1-ND
4	3	DNP	C6,C7,C8	CAP CER 0.1UF 10V 10% X5R 0402	MURATA	GRM155R61A104KA01D	490-1318-1-ND
5	1	10uF	C9	CAP CER 10UF 10V 10% X5R 0805	MURATA	GRM21BR61A106KE19L	490-1709-1-ND
6	1	0.1uF	C10	CAP CER 0.1UF 25V 10% X7R 0805	MURATA	GRM21BR71E104KA01L	490-1673-1-ND
7	2	4.7uF	C11,C13	CAP CER 4.7UF 16V 10% X7R 0805	AVX CORP	0805YC475KAT2A	478-5722-1-ND
8	2	DNP	C12,C14	CAP CER 4.7UF 16V 10% X7R 0805	AVX CORP	0805YC475KAT2A	478-5722-1-ND
9	1	470nF	C15	CAP CER 0.47UF 16V 10% X7R 0805	TDK	C2012X7R1C474K	445-1357-1-ND
10	1	22uF	C16	CAP CER 22UF 6.3V 20% X5R 0805	TDK	C2012X5R0J226M	445-1422-1-ND
11	3	0.1uF	C17,C19,C21	CAP CER 0.1UF 10V 10% X5R 0402	MURATA	GRM155R61A104KA01D	490-1318-1-ND
12	2	10uF	C18,C20	CAP CER 10UF 10V 10% X7R 0805	KEMET	C0805C106K8RACTU	399-7411-1-ND
13	2	0.1uF	C22,C23	CAP CER 0.1UF 16V 10% X7R 0603	AVX	0603YC104KAT2A	478-1239-1-ND
14	2	120 OHM @ 100MHz	FB1,FB2	FERRITE CHIP 120 OHM 3500MA 1206	MURATA	BLM31PG121SN1	490-1056-1-ND
15	2	SHUNT 2-3	JP1,JP2	CONN HEADER 3POS .25 GLD	SAMTEC	HMTSW-103-07-G-S-240	HMTSW-103-07-G-S-240-ND
16	1	SHUNT 1-2	JP3	CONN HEADER 3POS .25 GLD	SAMTEC	HMTSW-103-07-G-S-240	HMTSW-103-07-G-S-240-ND
17	5	SMA-END JACK 142-0701-801_ROUND	J1,J2,J3,J4,J7	CONN SMA JACK 50 OHM EDGE MNT	Johnson Components	142-0701-801	J502-ND
18	2	CONN JACK BANANA UNINS PANEL MOU	J5,J6	CONN JACK BANANA UNINS PANEL MOU	Emerson Network Power Connect	108-0740-001	J147-ND
19	4	GND Test Point	MTG1,MTG2,MTG3,MTG4	TEST POINT PC MINI .040"D BLACK	Keystone	5001	5001K-ND
20	2	976	R1,R2	RES 976 OHM 1/10W 1% 0402 SMD	PANASONIC	ERJ-2RKF9760X	P976LCT-ND
21	2	2K	R3,R4	RES 2K OHM 1/10W 1% 0402 SMD	PANASONIC	ERJ-2RKF2001X	P2.00KLCT-ND
22	2	DNP	R5,R6	RES 40.2 OHM 1/10W 1% 0402 SMD	PANASONIC	ERJ-2RKF40R2X	P40.2LCT-ND
23	2	121	R7,R8	RES 121 OHM 1/10W 1% 0402 SMD	PANASONIC	ERJ-2RKF1210X	P121LCT-ND
24	1	DNP	R9	RES 100 OHM 1/10W 5% 0402 SMD	PANASONIC	ERJ-2GEJ101X	P100JTR-ND
25	2	49.9	R10,R11	RES 49.9 OHM 1/10W 1% 0402 SMD	PANASONIC	ERJ-2RKF49R9X	P49.9LCT-ND
26	2	51.1	R12,R13	RES 51.1 OHM 1/10W 1% 0402 SMD	PANASONIC	ERJ-2RKF51R1X	P51.1LCT-ND
27	1	DNP	R14	RES 0.0 OHM 1/10W JUMP 0402 SMD	PANASONIC	ERJ-2GE0R00X	P0.0JCT-ND
28	2	10K	R15,R16	RES 10K OHM 1/10W 1% 0603 SMD	PANASONIC	ERJ-3EKF1002V	P10.0KHCT-ND
29	1	DNP	R17	RES 49.9 OHM 1/10W 1% 0603 SMD	PANASONIC	ERJ-3EKF49R9V	P49.9HCT-ND
30	1	THS4531ARUN	U1	IC AMP FDA ULT LOW PWR 10QFN	Texas Instruments	THS4531AIRUNR	THS4531AIRUNR-ND
31	1	LM7705	U2	IC REG SWITCHED CAP INV 8VSSOP	Texas Instruments	LM7705MM/NOPB	LM7705MM/NOPBCT-ND
32	3	SHUNT-JUMPER-0402	Z_SHUNT-J1,Z_SHUNT-J4,Z_SHUNT-J5	SHUNT FOR JUMPER	TE Connectivity	142270-3	A106360-ND
33	4	PANHEAD SCREW 4-40 x 3/8	Z_STANDOFF SCREW1,Z_STANDOFF SCREW2,Z_STANDOFF SCREW3,Z_STANDOFF SCREW4	SCREW FOR STANDOFF	Building Fasteners	PMS 440 0038 PH	H781-ND
34	4	STANDOFF ALUM HEX 4-40 x .750	Z_STANDOFF1,Z_STANDOFF2,Z_STANDOFF3,Z_STANDOFF4	STANDOFF	Keystone	2204	2204K-ND

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